



PATENT
Attorney Docket No.: SAM-0313

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Soo-geun Lee, *et al.*
Serial No.: 10/081,661
Filing Date: February 22, 2002
Title: METHOD OF MANUFACTURING INTERCONNECTION LINE IN SEMICONDUCTOR DEVICE

Examiner: Nguyen, H.
Group Art Unit: 2812

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July 2, 2003
Date

Lisa Sanders
Lisa Sanders

Mail Stop RCE
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Sir:

The amendments and remarks herein are intended to address the final Office Action mailed on March 6, 2003.

Please amend the application as follows:

In the Specification

Please delete the paragraph at page 6, lines 13-17.

In the Claims

Please amend the claims as follows:

1. (Twice Amended) A method of forming an interconnection line in a semiconductor device comprising:

forming a first etching stopper on a lower conductive layer which is formed on a semiconductor substrate;